



US03-001

Serial No. 10/802,563

January 29, 2008

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/802,563 03/17/04

Hong Yu Yu et al

"A THERMAL ROBUST SEMICONDUCTOR  
DEVICE USING HFN AS METAL GATE  
ELECTRODE AND THE MANUFACTURING  
PROCESS THEREOF"

Grp. Art Unit: 2823 SU C. KIM

RESPONSE FINAL PATENT OFFICE ACTION

Dear Sir:

In response to the Final Office Action dated November 1, 2007, please amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 30, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

[Signature]  
1/30/08

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 10 of this paper.